ABSTRACT

HIGH VOLUME FLUID HEAD

A new apparatus is provided for delivering cleaning agent to an apparatus for cleaning electrical components that are typically used in the semiconductor industry. The invention teaches an apparatus for the mass delivery of cleaning agent to the component that is being cleaned while this cleaning agent at the same time is delivered over a wide angle thereby covering an extensive area of the component that is being cleaned. At the same time, the angle under which the cleaning agent is delivered is such that the cleaning agent provides added impetus for the component that is being cleaned to remain in the position under which this component entered the cleaning chamber, this during the entire process of cleaning and drying.

(FIGURE 3 IS SUGGESTED FOR PUBLICATION)